

Full Material Declaration for attached parts list

Report generated: 21 September 2016, 12:15 GMT



Diotec Semiconductor AG

DUNS-Nummer: 330866844

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Declarations Autorisiert durch:

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Deklaration gilt ab: 1 January 2010 [Approved on 21 September 2016, 12:13 GMT]

Materialien und Stoffe

Verwendung/Andordnung	Material group	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Base material	Copper alloys	81.83000%	Copper	7440-50-8	100.00000%
Chip (die)	Other inorganic materials	0.09000%	Silicon dioxide	60676-86-0	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethylsiloxane rubber	63394-02-5	25.00000%
			Silicone	7440-21-3	62.50000%
Die attach	Sn-Pb solder	0.11000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	6.76000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			Tetrabromobisphenol A	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Leadfinish	Tin plating	0.07000%	Nickel	8049-31-8	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	8.61000%	Copper	7440-50-8	100.00000%
Plating	Copper plating	2.53000%	Nickel	7440-02-0	100.00000%

Beigefügte Artikelliste

Part number	Artikelbezeichnung	Artikelmasse	Artikelmasse UoM
BYPxx/BYZxx	Pressfit	7	g